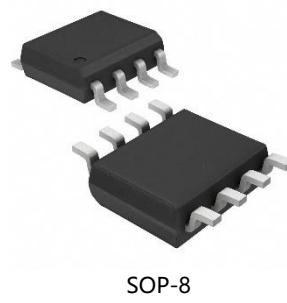


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HX2005-S 250V

Integrated bootstrap single-phase high and low side power MOSFET/IGBT driver chip

The HX2005-S is a high-voltage, high-speed power MOSFET high-low driver chip with separate high-side and low-side reference output channels. The chip adopts high and low voltage compatible technology, which makes the high and low side grid driving circuits can be integrated in a single chip. Its logic input levels are compatible with CMOS or LSTTL logic output levels as low as 3.3V. The output has high current pulse capability and straight-through dead-zone logic. The floating channel of the HX2005-S can be used to drive the N-channel power MOSFETs on the high voltage side, and the floating channel can operate up to 250V. The chip is packaged in SOP-8 and can operate in a temperature range of -40 °C to 125 °C. The HX2005-S integrates a bootstrap diode to charge the high side and simplify the peripheral circuit of the chip.



SOP-8

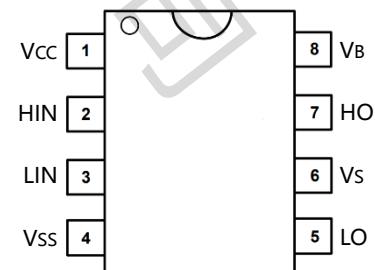
Peculiarity

- Floating channel for bootstrap work
- maximum working voltage: 250v
- Compatible input logic: 3.3v, 5v and 15v
- vs Negative bias capability: -9v
- dv/dt tolerance: ±50v/ns
- Range of gate driving voltage: 10v to 20v
- Anti direct dead zone logic
Dead time setting: 520ns
- Chip transmission delay characteristics
Enable/disable transmission delay: ton/toff = 160ns/150ns
Delay matching time: 60ns
- Integrated undervoltage locking circuit
Under voltage locking forward threshold: 8.9v
Undervoltage lockout negative threshold: 8.2v
- wide temperature range: -40°C to 125°C
- Output stage current pulling/pouring capability: 290ma/600ma
- Packaging type: SOP-8

Application

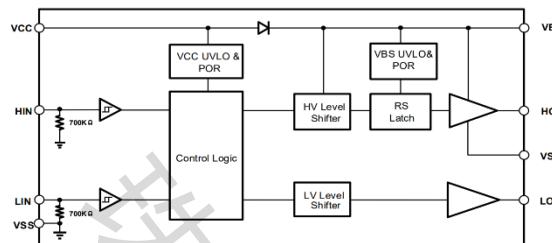
- Micro inverter drive
- Motor control
- Air conditioning/washing machine
- Universal inverter
- MOSFET/IGBT Driver chip

Chip pin description		
ID	Name	Function
1	Vcc	power supply
2	HIN	High side signal input
3	LIN	Low side signal input
4	Vss	Ground
5	LO	Low side output
6	Vs	High side floating ground
7	HO	High side output
8	Vb	High side floating power supply

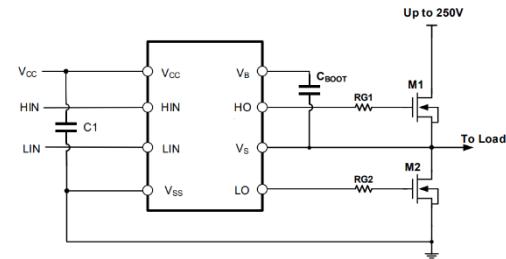


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Functional Block Diagram



Typical application circuit diagram



Specifications

Product specifications

Maximum operating range

Symbol	Definition	Min	Max	Unit
V _B	High side floating power supply voltage	-0.3	275	V
V _S	High side floating ground voltage	V _B - 25	V _B + 0.3	
V _{HO}	High side output voltage	V _S - 0.3	V _B + 0.3	
V _{CC}	Low side supply voltage	-0.3	25 1	
V _{LO}	Low side output voltage	COM -0.3	V _{CC} + 0.3	
V _{IN}	Logic input voltage	COM-0.3	V _{CC} + 0.3	
dVs/dt	Allow transient VS voltage conversion rate		50	V/ns

ESD RATING

ESD	HBM	1.5		kV
	Machine discharge mode	500		V

rated power

P _D	Encapsulation power (TA ≤ 25°C)		0.625	W
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Thermal information

R _{thJA}	thermal resistance		200	°C/W
T _J	Junction temperature		150	°C
T _S	storage temperature	-55	150	
T _L	Pin temperature		300	

Recommended scope of work

V _B	High side floating power supply voltage	V _S + 10	20	V
V _S	High side floating ground voltage	COM-9 2	250	
V _{HO}	High side output voltage	V _S	V _B	
V _{CC}	Low side supply voltage	10	20	
V _{LO}	Low side output voltage	COM	V _{CC}	
V _{IN}	Logic input voltage	0	V _{CC}	
T _A	ambient temperature	-40	125	

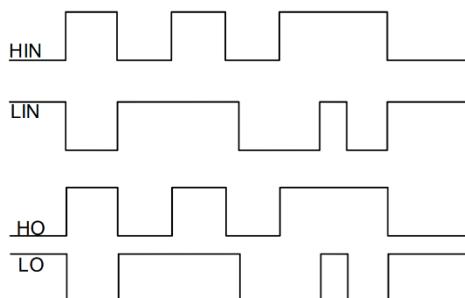
Note: 1 All power sources tested at 25V

2To ensure the normal operation of the chip, please ensure that it operates between -8V-200V

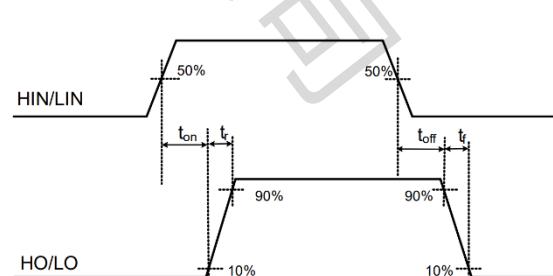
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Electrical characteristics Unless otherwise specified $T_A = 25^\circ C$, $V_{CC} = V_B = 15V$, $C_L = 1nF$						
Dynamic parameter characteristics						
Symbol	Definition	Min	Typ	Max	Unit	Test condition
t_{ON}	Enable transmission delay		150	220	ns	$V_S = 0/250V$
t_{OFF}	Turn off transmission delay		150	220		$V_S = 0V$
t_R	Enable rise time		70	170		
t_F	Close the descent time		30	90		
t_M	Delay matching time (t_{ON} , t_{OFF})			60		
Static parameters have no special description $V_{CC} = V_{BS} = 15V$, $T_A = 25^\circ C$						
V_{CCUV+}	V_{CC} Under voltage positive threshold	8.0	8.9	9.8	V	
V_{CCUV}	V_{CC} Undervoltage negative threshold	7.4	8.2	9		
V_{BSUV+}	V_{BS} Under voltage positive threshold	8.0	8.9	9.8		
V_{BSUV-}	V_{BS} Undervoltage negative threshold	7.4	8.2	9		
I_{LK}	Leakage current of high side floating power supply			50	μA	$V_B = V_S = 250V$
I_{QBS}	V_{BS} static current		50	75	μA	All inputs are in a closed state
I_{QCC}	V_{CC} static current		120	250	μA	
V_{IH}	Input logic high-level threshold voltage	2.5			V	$V_{CC} = 10V$ to $20V$
V_{IL}	Input logic low threshold voltage			0.8		
V_{OH}	Output high-level voltage drop $V_{BIAS} - V_O$		0.05	0.2		$I_O = 2mA$
V_{OL}	Output low-level voltage drop V_O		0.02	0.1		
I_{IN+}	Logic "1" Input bias current		3	10	μA	$V_{IN} = 5V$
I_{IN-}	Logic '0' input bias current			5	μA	$V_{IN} = 0V$
I_{O+}	Output pulling current	200	290		mA	$V_O = 0V$ $PW \leq 10\mu s$
I_{O-}	Output current injection	420	600		mA	$V_O = 15V$ $PW \leq 10\mu s$
R_{BSD}	Internal resistance of bootstrap diode		200		Ω	$I_{BSD} = 1mA$
V_{BSD}	Bootstrap diode conduction voltage drop		0.6		V	$I_{BSD} = 1mA$

Input and output waveform diagram

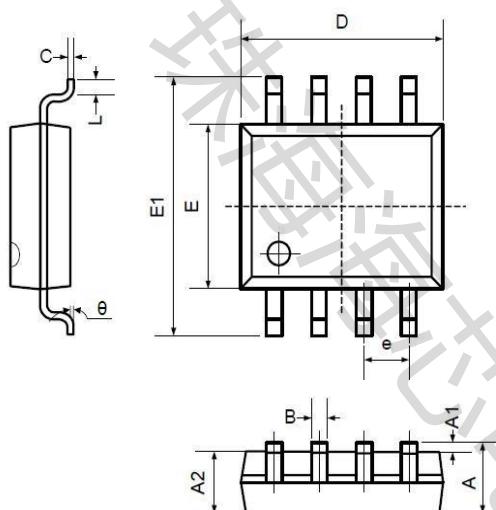


Switching waveform

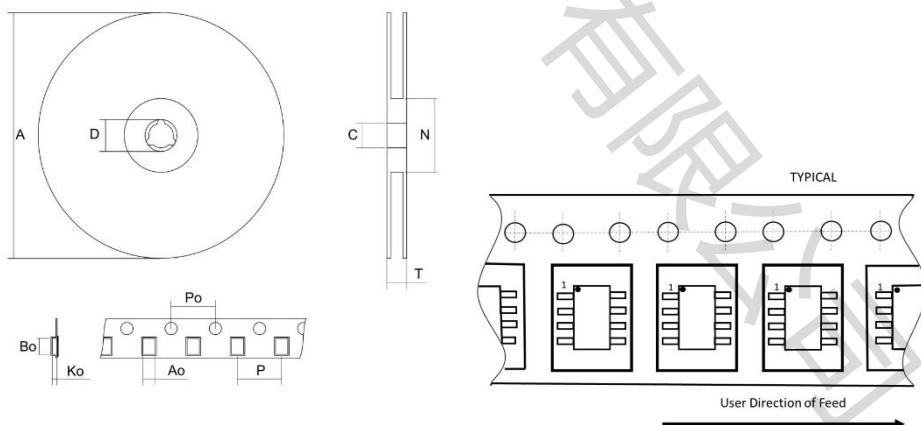


Packaging and packaging

SOP8 (Package Outline Dimensions)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
B	0.330	0.510	0.013	0.020
C	0.190	0.250	0.007	0.010
D	4.780	5.000	0.188	0.197
E	3.800	4.000	0.150	0.157
E1	5.800	6.300	0.228	0.248
e	1.270TYP		0.050TYP	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Packing method	Number
Braid	2500PCS/Disk